

## **Product Bulletin**

Document # : PB20849X Issue Date: 8 December 2015

Title of Change:		Announcement of lead frame raw material change (PKG name: MFP16FS).			
Effective date:		8 December 2015			
Contact information:		Contact your local ON Semiconductor Sales Office or < <a href="mailto:tetsuya.fukushima@onsemi.com">tetsuya.fukushima@onsemi.com</a> >			
Type of notification:		ON Semiconductor will consider this change accepted.			
Chang	ge category:	☐ Wafer Fab Change			
Change Sub-Category(s):					_
Sites Affected:  All site(s) not applicable  ON Semiconductor site(s):  ON Tarlac City, Philippines					
Description and Purpose:					
The reason is that the existing lead frame raw material will be end of life by January 2016.  We will replace the existing lead frame raw material C18020 with C19400 (C18020/C19400: ASTM code).  The table below shows comparison of mechanical and chemical properties between two materials.					
	Material Na	ıme	C19400 (alternative)	C18020 (Existing)	
	Mechanical properties				
	Coefficient of Thermal Expansion	X10 <sup>-8</sup> /K	17.6	17.0	
	Thermal Conductivity	W (m· K)	262	315	
	Electrical Resistivity	μΩm	0.025	0.021	
	Electrical Conductivity	/ %IACS	65	75	
	Modulus Elasticity	KN/mm <sup>2</sup>	121	123	
	Chemical properties				
	Cu		Remain	Remain	
	Zn	%	0.05 ~ 0.20	0.10 ~ 0.30	
	PB	%	Max 0.03	None	
	Fe	%	2.10 ~ 2.60	None	
	Pb	%	0.01 ~ 0.15	None	
	Sn	%	None	Max 0.25	
List of affected Standard Parts:					
	LA6584M-MPB-E	7			
	LA6584M-MPB-H				
	LA6584M-TLM-E	_			
	LA6584M-TLM-H				

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